

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road San Jose, CA 95138 USA

Manufacturing Bulletin

Subject: BGA 4x4.5 mm (AD/ADG 28) Tray Conversion Date: 15 Aug 2011

This notification is to advise our customers that IDT has qualified a new shipping tray type for 4mm x 4.5mm BGA-28 package and will convert to the new shipping trays for shipment effective October 03, 2011.

There are changes in the tray pocket dimensions/design. However, there are no changes to tray outer dimensions and number of units per tray.

The new tray provides better protection against possible damage during transportation for customer shipments.

Refer to attachment I for new and old tray top view differences.

Trav Dimension:

Description	Existing Tray	New Tray
Tray Outer Dimens	tion 135.9 x 322.6 mm	135.9 x 322.6 mm
Length x Width		
Tray Pocket Dimens	tion 4.20 x 4.70 x 1.00 mm	4.25 x 4.75 x 1.30 mm
Length x Width x Depth		

Changes on New Trav:

Description	Reason for Change	
Pocket dimension/design	To ease the detection of double units inside tray pocket.	
	(refer to attachment II(a))	
Bottom tray pocket with 4	To prevent unit sticky problem due to ESD static. (refer	
humps	to attachment II(b))	

Yours sincerely,

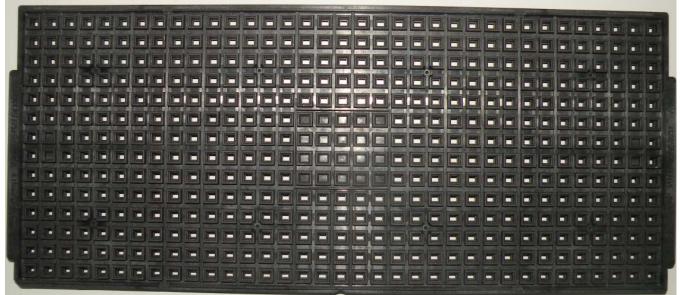
LS Koay Manage **Manager, Product Assurance** Integrated Device Technology (Malaysia) Sdn Bhd. lskoay@idt.com Tel. # (604) 613-2283 (Malaysia)



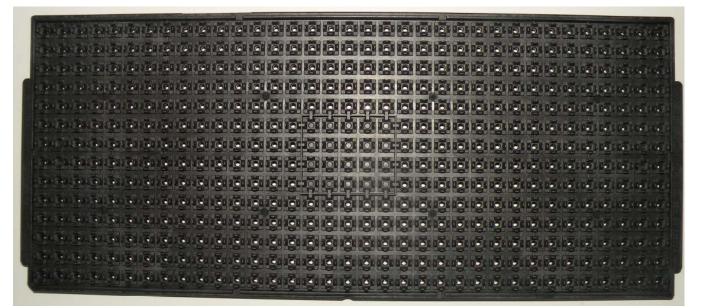
Manufacturing Bulletin Attachment I

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Old Tray (Top View)



New Tray (Top View)





<u>Manufacturing Bulletin</u> Attachment II

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(a) New Tray (has gap if double units per pocket)



(b) New Tray (Bottom tray pocket with 4 humps)

